

HIRP3015Q12-K6

SMD Type 850nm Infrared Emitter

Features

- Small double-end package
- Viewing Angle = $\pm 48^{\circ}$
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

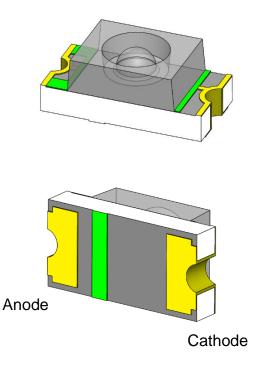
Applications

Infrared sensor

Description

The HIRP3015Q12-K6 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 850nm LED spectrally matched with phototransistor or photodiode.

Package Outline



Schematic





Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
IF	Continuous Forward Current	70	mA	
IFP	Peak Forward Current	0.7	А	1
V _R	Reverse Voltage	5	V	
T _{opr}	Operating Temperature	-40 ~ +85	٥C	
T _{stg}	Storage Temperature	-40 ~ +100	٥C	
T _{sol}	Soldering Temperature	260	٥C	2
PD	Power Dissipation at(or below) 25°C Free Air Temperature	140	mW	

Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

Optical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
le	Radiant Intensity	I _F =20mA	1.5	3.0	-	mW/sr	
		I _F =70mA	-	11	-	11100/51	
λр	Peak Wavelength	I _F =20mA	-	850	-	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	35	-	nm	
θ1/2	Angle of Half Intensity	I _F =20mA	-	±48	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward Voltage	I _F =20mA	1.30	1.40	1.7	- V	
		I _F =70mA	1.40	1.60	2.0		
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Notes:

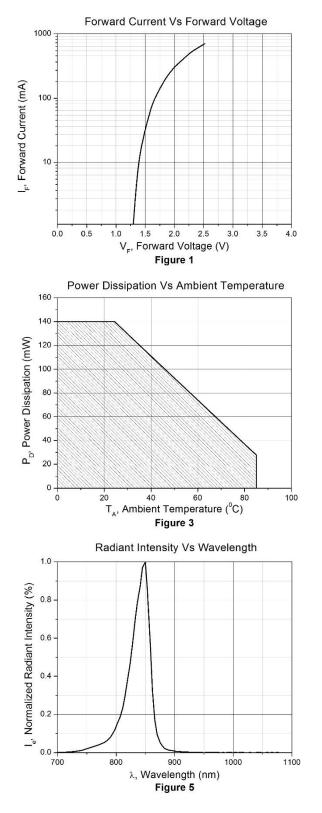
1. I_{FP} Conditions--Pulse Width $\leq ~100 \mu s$ and Duty $\leq ~1\%.$

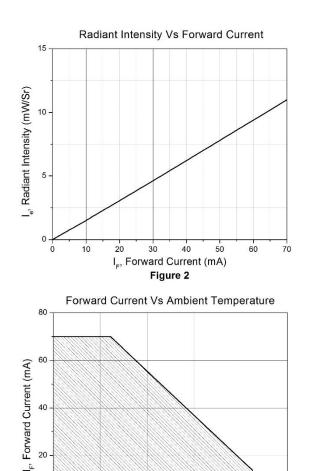
2. Soldering time \leq 5 seconds.



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Typical Characteristic Curves





20 40 60 T_A, Ambient Temperature (⁰C)

80

100

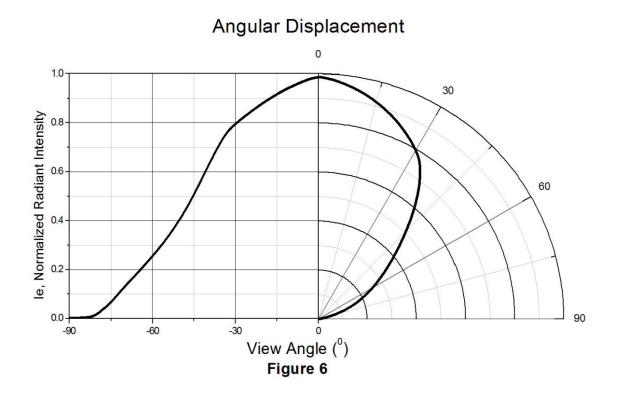
20

0

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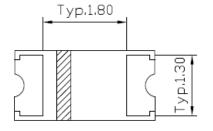


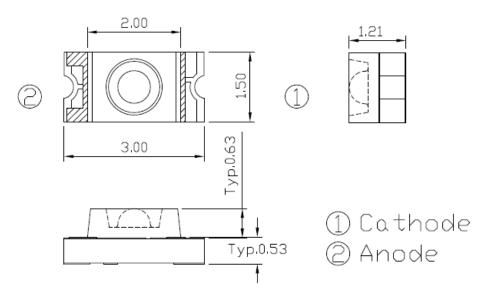
Typical Characteristic Curves



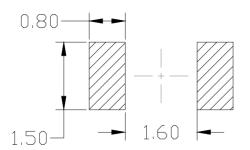


Package Dimension All dimensions are in mm, unless otherwise stated





Recommended Soldering Mask All dimensions are in mm, unless otherwise stated

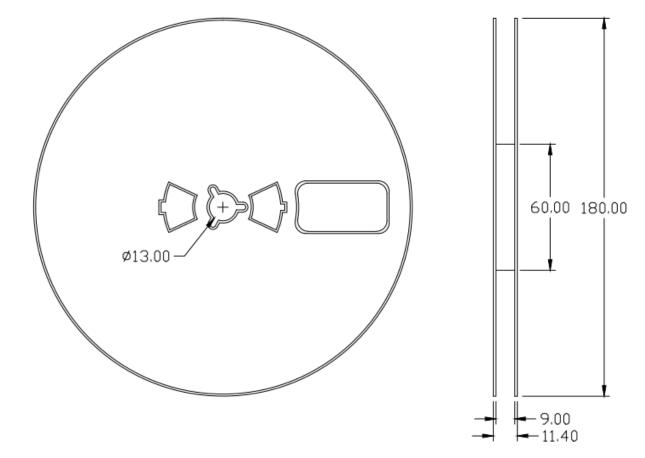


Ordering Information

Part Number	Description	Quantity
HIRP3015Q12-K6	Tape & Reel	3000 pcs

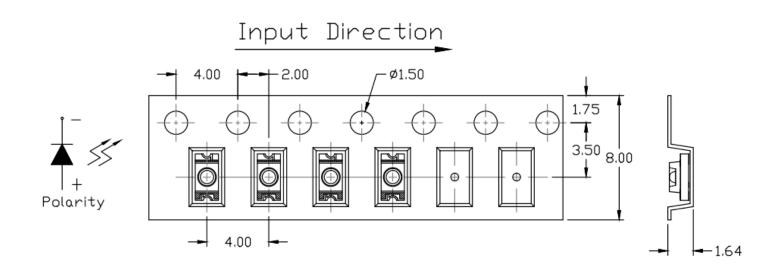


SMD Type 850nm Infrared Emitter



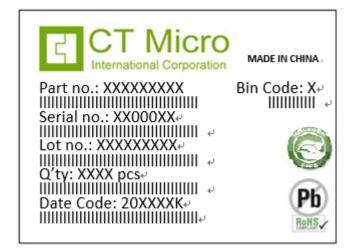
Reel Dimension All dimensions are in mm, unless otherwise stated

Tape Dimension All dimensions are in mm, unless otherwise stated





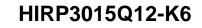
Label Form Specification



Part no: CTM Production Number Serial no: Production Number Lot no: Lot number Q'ty: Packing Quantity Date Code: Manufacture Date Bin Code: Ie Ranks MADE IN CHINA: Production Place

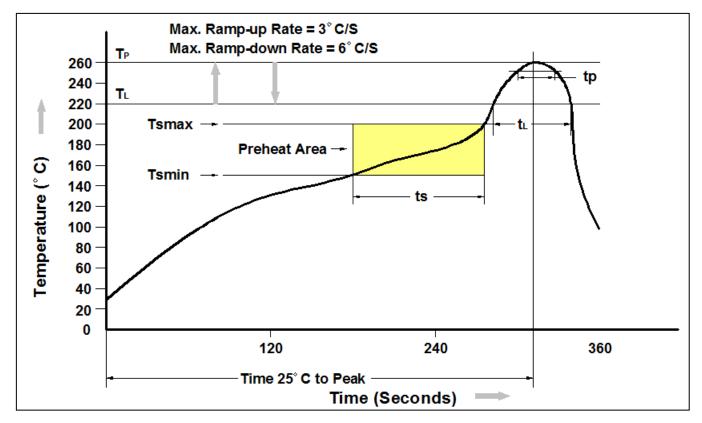
Storage Condition

- 1. Do not open moisture proof bag before the products are ready to use.
- 2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening. Shelf life of non-opened bag is 12 months after the bag sealing date.
- 3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
- 4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.





Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



IRP2406T14-B50 SMD Type 940nm Infrared Emitter